

HIGH DENSITY SINGLE INLINE MEMORY MODULE

ABSTRACT OF THE DISCLOSURE

A high density single inline memory module (140) comprising a printed circuit board (132) and at least one integrated circuit module (130) attached to the first side (134) of the printed circuit board (132), wherein the integrated circuit modules (130) each including first and second integrated circuit packages (30) stackably and electrically connected together is disclosed.

Figure 1

This Sheet Has Been Replaced

